

# TDSEMIC

## 拓電半導體

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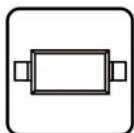
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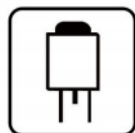
電源管理



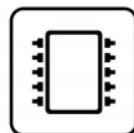
照 示驅動



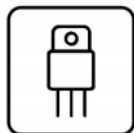
二三極管



LDO穩壓器



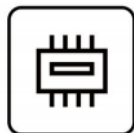
觸摸芯片



MOS管



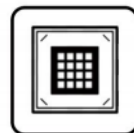
運算放大器



存備芯片



MCU



串口通信

# HT7833-TD

產品規格說明書

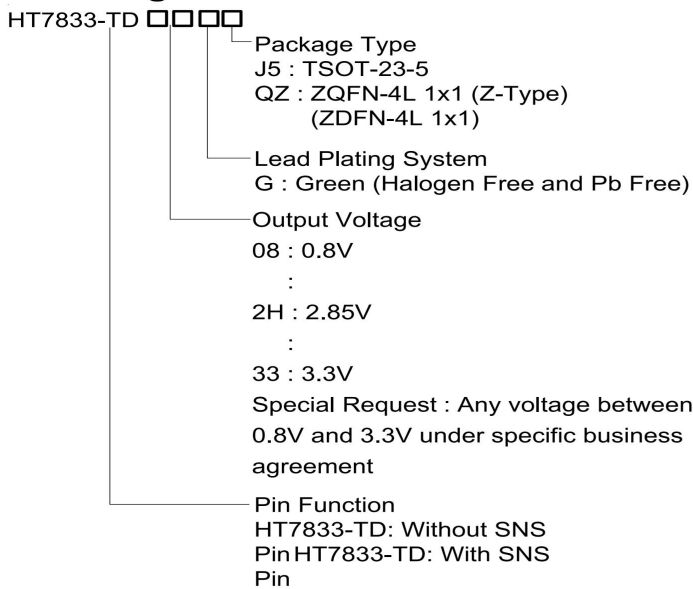
## 2μA I<sub>Q</sub>, 600mA Low-Dropout Linear Regulator

### General Description

The HT7833-TD is a low-dropout (LDO) voltage regulator with enable function that operates from 1.2V to 5.5V. It provides up to 600mA of output current and offers low-power operation in miniaturized packaging.

The features of low quiescent current as low as 2μA and almost zero disable current is ideal for powering the battery equipment to a longer service life. The HT7833-TD is stable with the ceramic output capacitor over its wide input range from 1.2V to 5.5V and the entire range of output load current (0mA to 600mA).

### Ordering Information



### Features

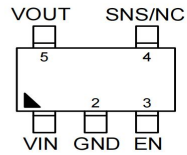
- 2μA Ground Current at no Load
- PSRR = 75dB at 1kHz
- Adjustable Output Voltage Available by Specific Application
- ±2% Output Accuracy
- 600mA (V<sub>IN</sub> ≥ 2.3V) Output Current with EN
- Low (0.1μA) Disable Current
- 1.2V to 5.5V Operating Input Voltage
- Dropout Voltage : 0.31V at 600mA when V<sub>OUT</sub> ≥ 3V
- Support Fixed Output Voltage 0.8V to 3.3V
- Stable with Ceramic or Tantalum Capacitor
- Current-Limit Protection
- Over-Temperature Protection
- TSOT-23-5 and ZQFN-4L 1x1 (ZDFN-4L 1x1) Packages Available

### Applications

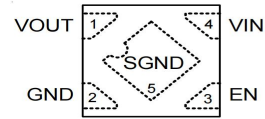
- Portable, Battery Powered Equipment
- Ultra Low Power Microcontrollers
- Notebook Computers

## Pin Configuration

(TOP VIEW)



TSOT-23-5

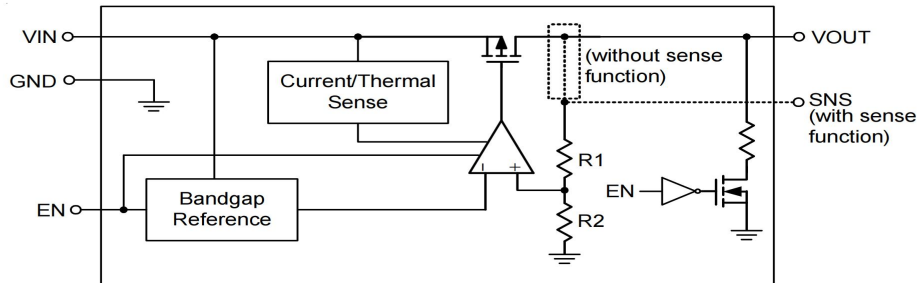


ZQFN-4L 1x1 (ZDFN-4L 1x1)

## Functional Pin Description

Pin No.		Pin Name	Pin Function
TSOT-23-5	ZQFN-4L 1x1 (ZDFN-4L 1x1)		
1	4	VIN	Supply voltage input.
2	2	GND	Ground.
3	3	EN	Enable control input.
4	--	SNS Output	voltage sense. (AC3080N only)
		NC	No internal connection.
5	1	VOUT	Output of the regulator.
--	5 (Exposed Pad)	SGND	Substrate of chip. Leave floating or tie to GND.

## Functional Block Diagram



## Operation

### Basic Operation

The HT7833-TD is a low quiescent current linear regulator designed especially for low external components system. The input voltage range is from 1.2V to 5.5V.

The minimum required output capacitance for stable operation is 1 $\mu$ F effective capacitance after consideration of the temperature and voltage coefficient of the capacitor.

### Output Transistor

The HT7833-TD builds in a P-MOSFET output transistor which provides a low switch-on resistance for low dropout voltage applications.

### Error Amplifier

The Error Amplifier compares the internal reference voltage with the output feedback voltage from the internal divider, and controls the Gate voltage of P-MOSFET to support good line regulation and load regulation at output voltage.

### Enable

The HT7833-TD delivers the output power when it is set to enable state. When it works in disable state, there is no output power and the operation quiescent current is almost zero.

### Current-Limit Protection

The HT7833-TD provides current limit function to prevent the device from damages during over-load or shorted-circuit condition. This current is detected by an internal sensing transistor.

### Over-Temperature Protection

The over-temperature protection function will turn off the P-MOSFET when the junction temperature exceeds 150°C (typ.), and the output current exceeds 80mA. Once the junction temperature cools down by approximately 20°C, the regulator will automatically resume operation.

## Absolute Maximum Ratings (Note 1)

• VIN, VOUT, SNS, EN to GND	-----	-0.3V to 6.5V
• VOUT to VIN	-----	-6.5V to 0.3V
• Power Dissipation, P <sub>D</sub> @ T <sub>A</sub> = 25°C		
TSOT-23-5	-----	0.43W
ZQFN-4L 1x1 (ZDFN-4L 1x1)	-----	0.44W
• Package Thermal Resistance (Note 2)		
TSOT-23-5, θ <sub>JA</sub>	-----	230.6°C/W
TSOT-23-5, θ <sub>JC</sub>	-----	21.8°C/W
ZQFN-4L 1x1 (ZDFN-4L 1x1), θ <sub>JA</sub>	-----	226°C/W
ZQFN-4L 1x1 (ZDFN-4L 1x1), θ <sub>JC</sub>	-----	43°C/W
• Lead Temperature (Soldering, 10 sec.)	-----	260°C
• Junction Temperature	-----	150°C
• Storage Temperature Range	-----	-65°C to 150°C
• ESD Susceptibility (Note 3)		
HBM (Human Body Model)	-----	2kV

## Recommended Operating Conditions (Note 4)

• Input Voltage, VIN	-----	1.2V to 5.5V
• Junction Temperature Range	-----	-40°C to 125°C
• Ambient Temperature Range	-----	-40°C to 85°C

## Electrical Characteristics

(V<sub>OUT</sub> + 1 < V<sub>IN</sub> < 5.5V, T<sub>A</sub> = 25°C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Output Voltage Range	V <sub>OUT</sub>		0.8	--	3.3	V
DC Output Accuracy		I <sub>LOAD</sub> = 1mA	-2	--	2	%
Dropout Voltage (I <sub>LOAD</sub> = 600mA) (Note 5)	V <sub>DROP</sub>	0.8V ≤ V <sub>OUT</sub> < 1.05V (TSOT-23-5)	--	1.05	1.33	V
		0.8V ≤ V <sub>OUT</sub> < 1.05V (ZQFN-4L 1x1)	--	1.05	1.63	
		1.05V ≤ V <sub>OUT</sub> < 1.2V	--	0.8	1.13	
		1.2V ≤ V <sub>OUT</sub> < 1.5V	--	0.71	1.03	
		1.5V ≤ V <sub>OUT</sub> < 1.8V	--	0.57	0.93	
		1.8V ≤ V <sub>OUT</sub> < 2.1V	--	0.57	0.83	
		2.1V ≤ V <sub>OUT</sub> < 2.5V	--	0.41	0.73	
		2.5V ≤ V <sub>OUT</sub> < 3V	--	0.36	0.63	
		3V ≤ V <sub>OUT</sub>	--	0.31	0.53	
V <sub>CC</sub> Consumption Current	I <sub>Q</sub>	I <sub>LOAD</sub> = 0mA, V <sub>OUT</sub> ≤ 5.5V V <sub>IN</sub> ≥ V <sub>OUT</sub> + V <sub>DROP</sub>	--	2	4	μA
Shutdown GND Current (Note 6)		V <sub>EN</sub> = 0V	--	0.1	0.5	μA
Shutdown Leakage Current (Note 6)		V <sub>EN</sub> = 0V, V <sub>OUT</sub> = 0V	--	0.1	0.5	μA

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit	
EN Input Current	I <sub>EN</sub>	V <sub>EN</sub> = 5.5V	--	--	0.1	μA	
Line Regulation	ΔLINE	I <sub>LOAD</sub> = 1mA	1.2V ≤ V <sub>IN</sub> < 1.5V	--	0.3	0.6	%
			1.5V ≤ V <sub>IN</sub> < 1.8V	--	0.15	0.3	
			1.8V ≤ V <sub>IN</sub> < 5.5V	--	0.13	0.35	
Load Regulation	ΔLOAD	1mA < I <sub>LOAD</sub> < 600mA	--	0.5	1	%	
Power Supply Rejection Ratio	PSRR	V <sub>IN</sub> = 3V, I <sub>LOAD</sub> = 50mA, C <sub>OUT</sub> = 1μF, V <sub>OUT</sub> = 2.5V, f = 1kHz	--	75	--	dB	
Output Voltage Noise		C <sub>OUT</sub> = 1μF, I <sub>LOAD</sub> = 150mA, BW = 10Hz to 100kHz, V <sub>IN</sub> = V <sub>OUT</sub> + 1V	V <sub>OUT</sub> = 0.8V	--	26	--	μVRMS
			V <sub>OUT</sub> = 1.2V	--	37	--	
			V <sub>OUT</sub> = 1.8V	--	39	--	
			V <sub>OUT</sub> = 3.3V	--	42	--	
Output Current Limit	I <sub>LIM</sub>	V <sub>OUT</sub> = 90%V <sub>OUT(Normal)</sub>	610	1100	--	mA	
Enable Input Voltage	Logic-High	V <sub>IH</sub>	V <sub>IN</sub> = 5V	0.9	--	--	V
	Logic-Low	V <sub>IL</sub>	V <sub>IN</sub> = 5V	--	--	0.4	
Thermal Shutdown Temperature	T <sub>SD</sub>	I <sub>LOAD</sub> = 30mA, V <sub>IN</sub> ≥ 1.5V	--	150	--	°C	
Thermal Shutdown Hysteresis	ΔT <sub>SD</sub>		--	20	--	°C	
Discharge Resistance		EN = 0V, V <sub>OUT</sub> = 0.1V	--	80	--	Ω	

**Note 1.** Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

**Note 2.** θ<sub>JA</sub> is measured in the natural convection at T<sub>A</sub> = 25°C on a two-layer Richtek Evaluation Board for ZQFN-4L 1x1 (ZDFN-4L1x1) Package.

θ<sub>JA</sub> is measured at T<sub>A</sub> = 25°C on a high effective thermal conductivity four-layer test board per JEDEC 51-7 for TSOT-23-5 Package.

**Note 3.** Devices are ESD sensitive. Handling precaution is recommended.

**Note 4.** The device is not guaranteed to function outside its operating conditions.

**Note 5.** The dropout voltage is defined as V<sub>IN</sub> - V<sub>OUT</sub>, when V<sub>OUT</sub> is 98% of the normal value of V<sub>OUT</sub>.

**Note 6.** The specification is tested at wafer stage and guarantee by design after assembly.

## Typical Application Circuit

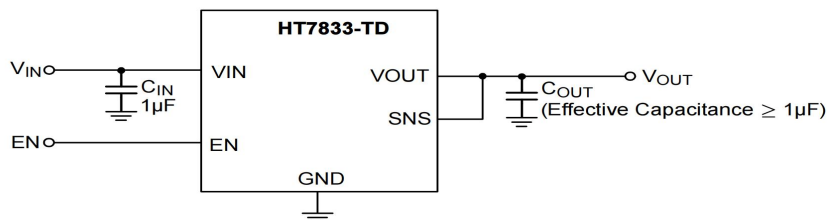


Figure 1. Application with Sense Function

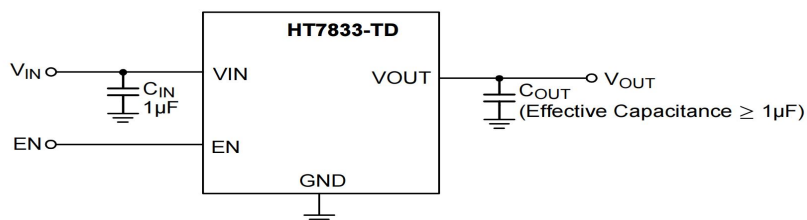


Figure 2. Application without Sense Function

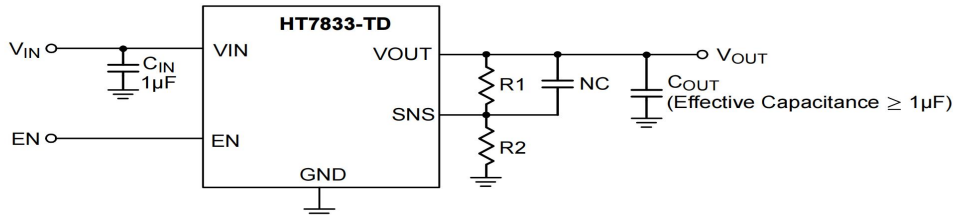
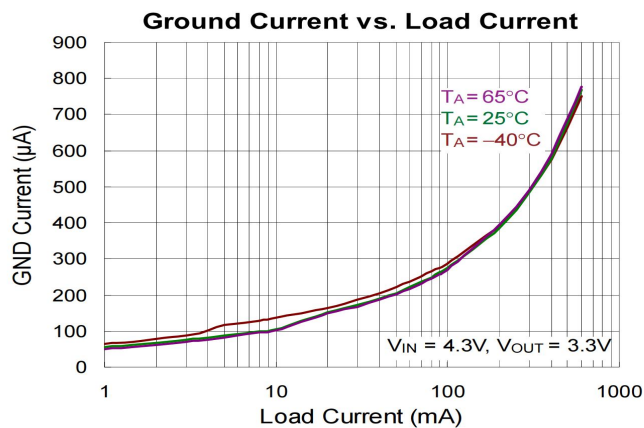
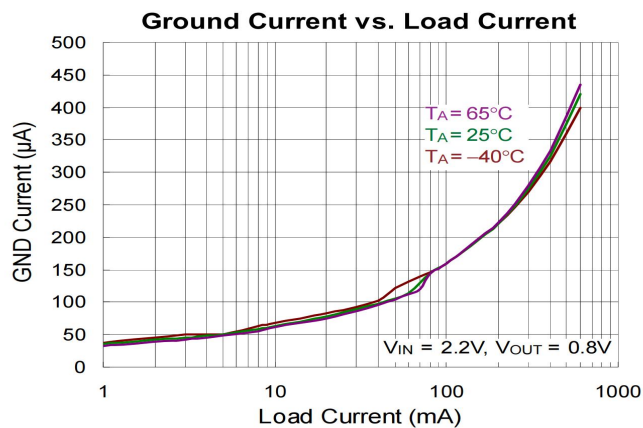
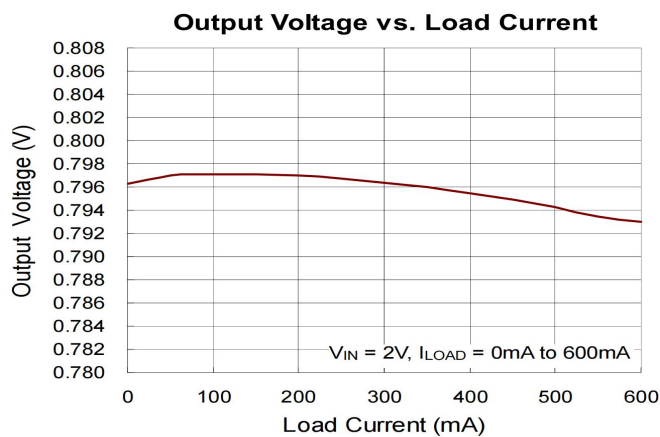
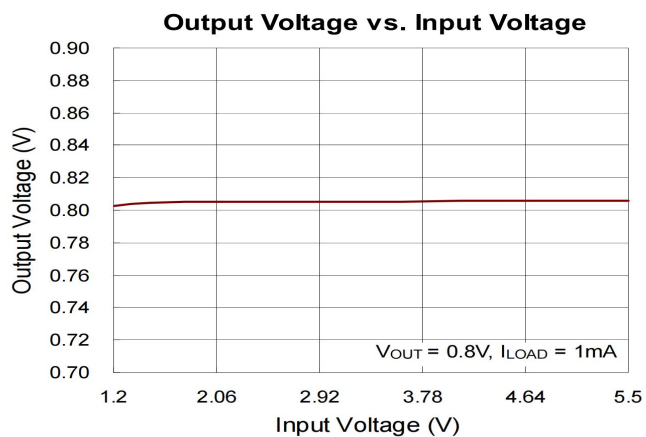
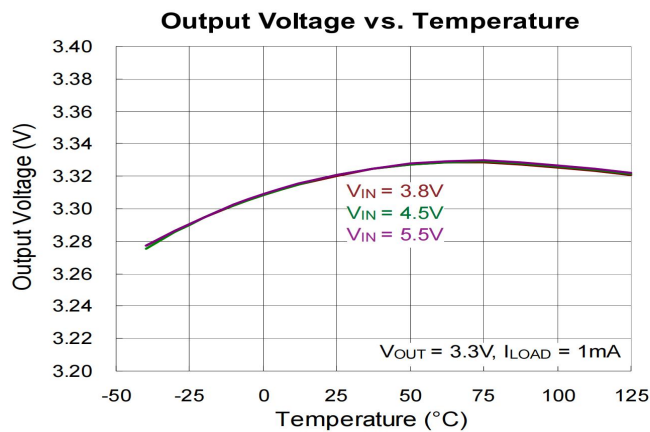
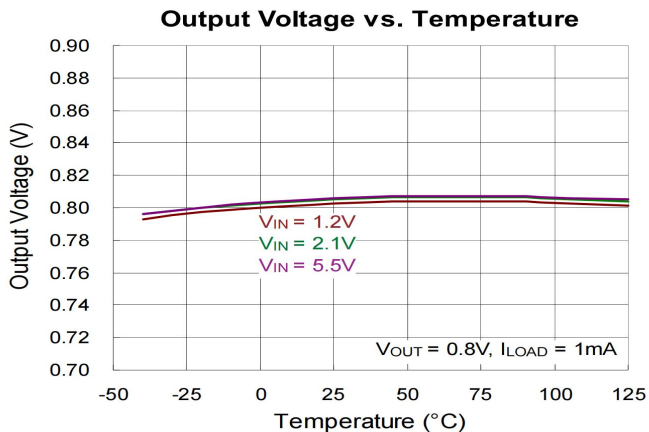
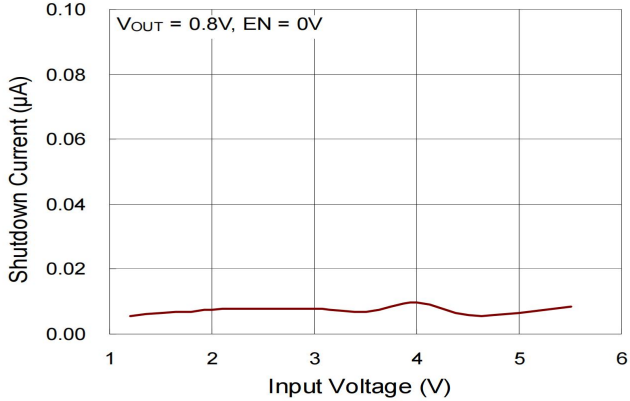


Figure 3. Adjustable Output Voltage Application Circuit

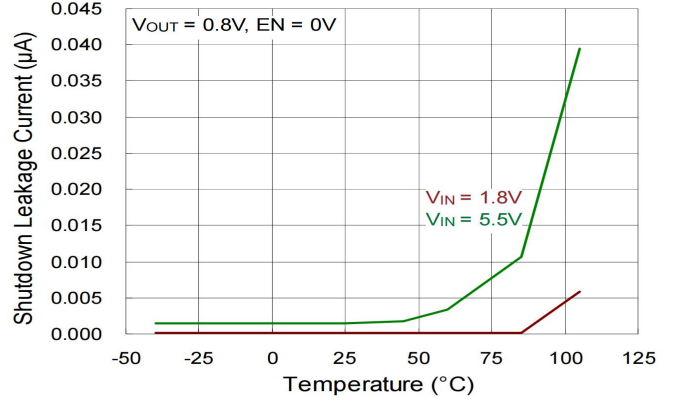
## Typical Operating Characteristics



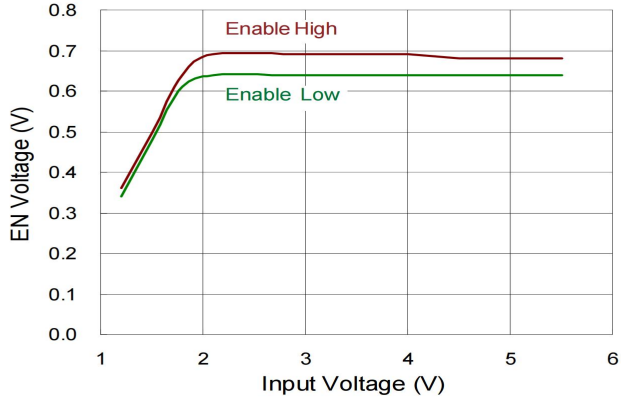
### Shutdown Current vs. Input Voltage



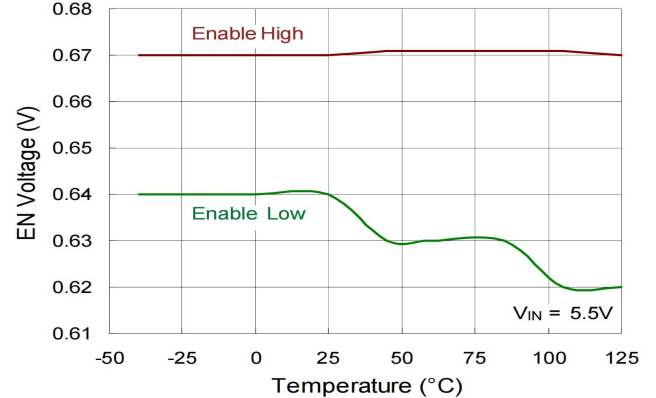
### Shutdown Leakage Current vs. Temperature



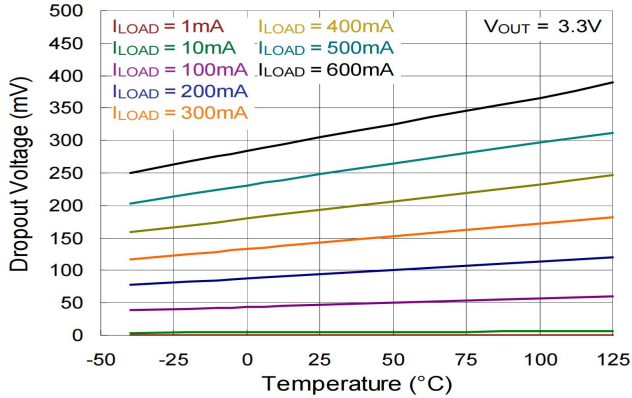
### Enable Threshold vs. Input Voltage



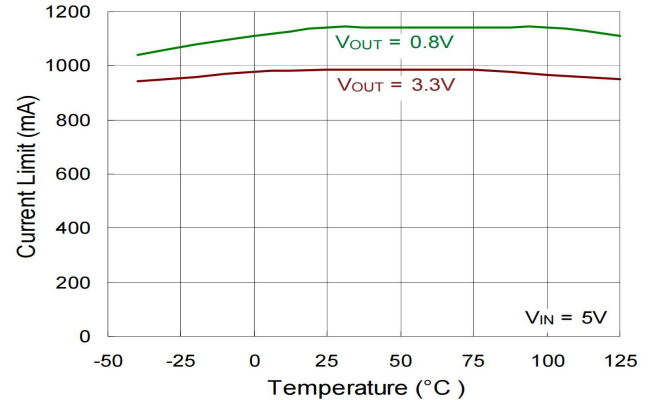
### Enable Threshold vs. Temperature



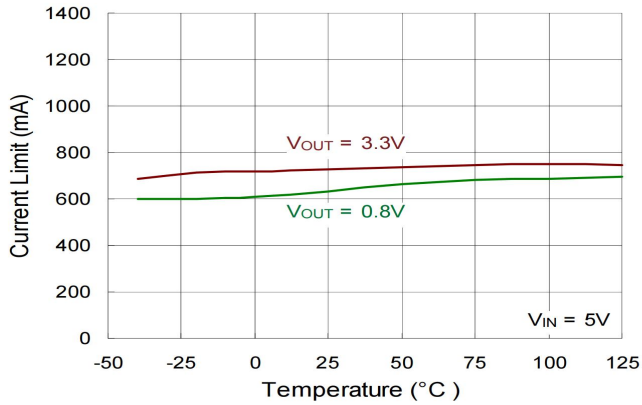
### Dropout Voltage vs. Temperature



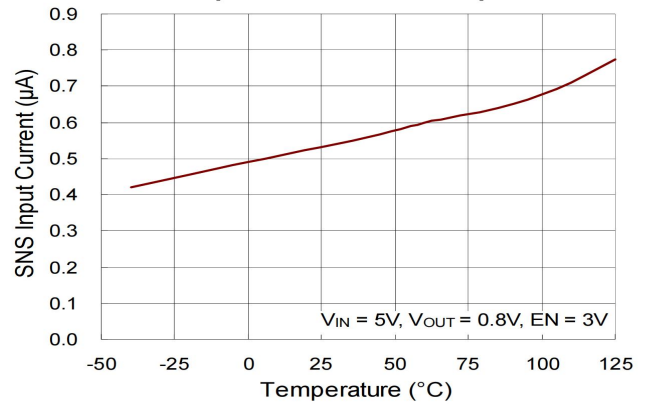
### Current Limit vs. Temperature



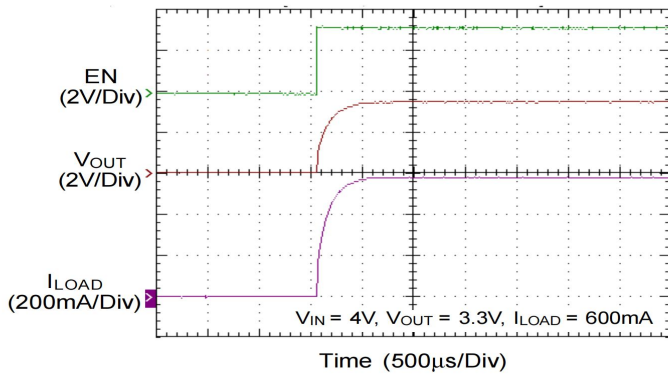
**Fold-Back Current Limit vs. Temperature**



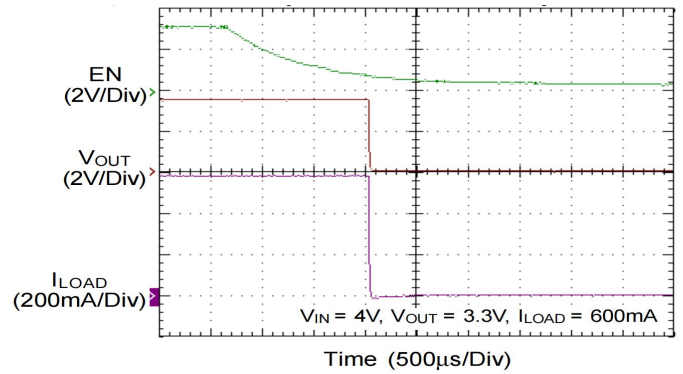
**SNS Input Current vs. Temperature**



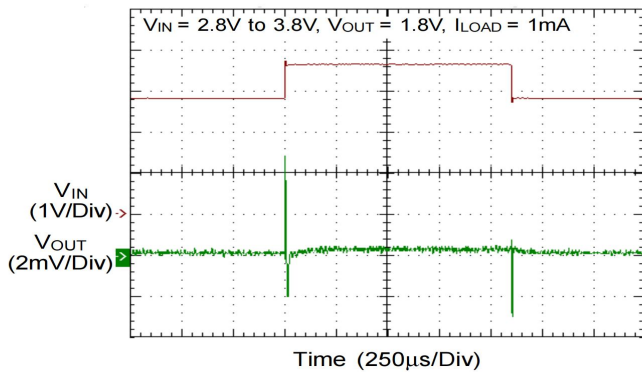
**Power On from EN**



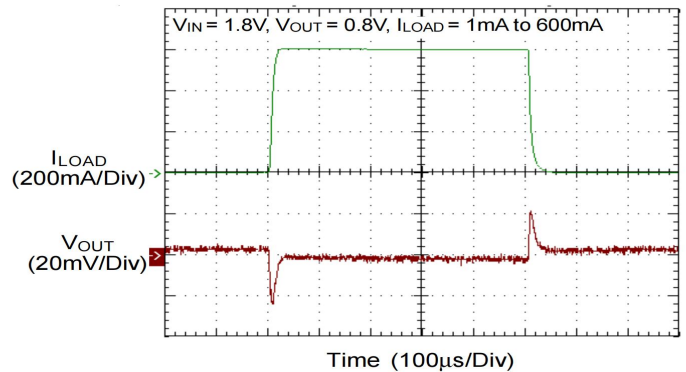
**Power Off from EN**

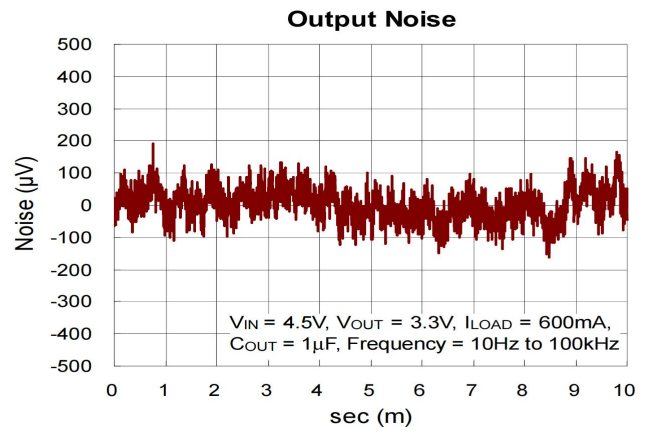
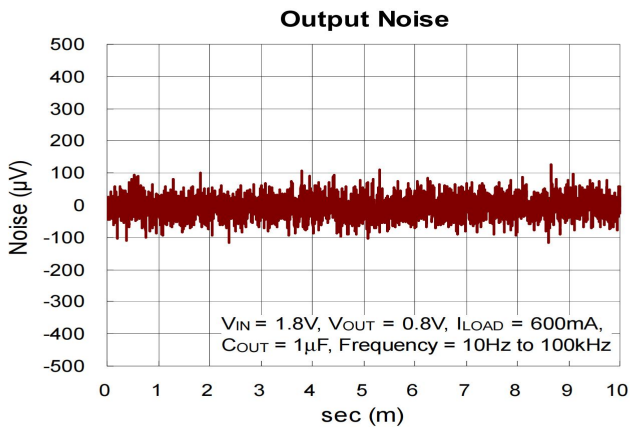
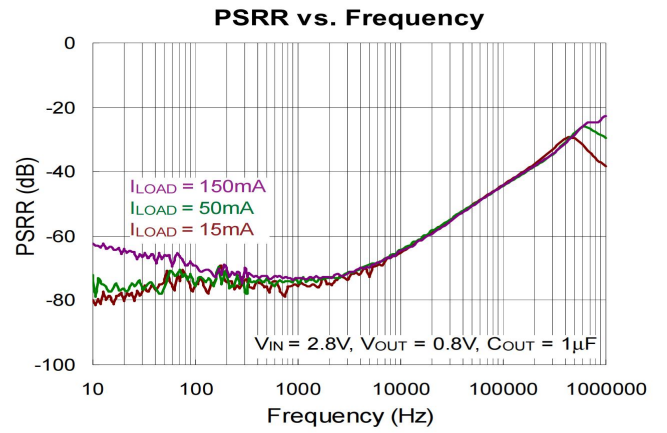
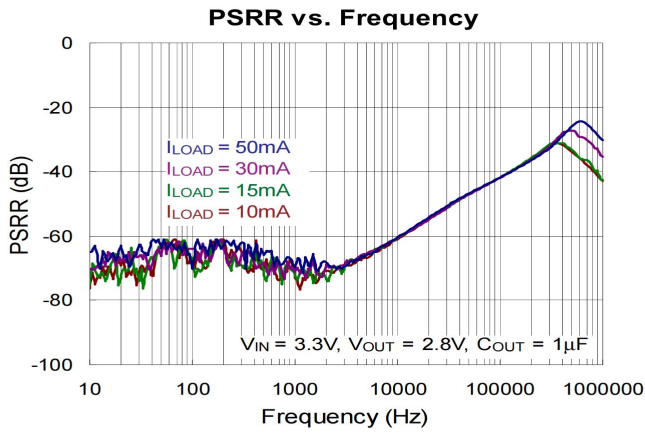


**Line Transient**



**Load Transient**





## Application Information

Like any low dropout linear regulator, the HT7833-TD's external input and output capacitors must be properly selected for stability and performance. Use a 1μF or larger input capacitor and place it close to the IC's VIN and GND pins. Any output capacitor meeting the minimum 1mΩ ESR (Equivalent Series Resistance) and effective capacitance larger than 1μF requirement may be used. Place the output capacitor close to the IC's VOUT and GND pins. Increasing capacitance and decreasing ESR can improve the circuit's PSRR and line transient response.

### Enable

The HT7833-TD has an EN pin to turn on or turn off the regulator. When the EN pin is in logic high, the regulator will be turned on. The shutdown current is almost 0μA typical. The EN pin may be directly tied to VIN to keep the part on. The Enable input is CMOS logic and cannot be left floating.

### Adjustable Output Voltage Setting

Because of the small input current at the SNS pin, the HT7833-TD with SNS pin also can work as an adjustable output voltage LDO. Figure 3 gives the connections for the adjustable output voltage application. The resistor divider from VOUT to SNS sets the output voltage when in regulation.

The voltage on the SNS pin sets the output voltage and is determined by the values of R1 and R2. In order to keep a good temperature coefficient of output voltage, the values of R1 and R2 should be selected carefully to ignore the temperature coefficient of input current at the SNS pin. A current greater than 50μA in the resistor divider is recommended to meet the above requirement. The adjustable output voltage can be calculated using the formula given in equation 1 :

$$V_{OUT} = \frac{R1 + R2}{R2} \times V_{SNS} \quad (1)$$

where  $V_{SNS}$  is determined by the output voltage selections in the ordering information of the HT7833-TD. The maximum adjustable output voltage can be as high as input voltage deducted by the dropout voltage.

When we choose 51kΩ and 16kΩ as R1 and R2 respectively, and select a 0.8V output at SNS pin, the

adjustable output voltage will be set to around 3.35V. Its temperature coefficient in Figure 4 is still perfect in such kind of application.

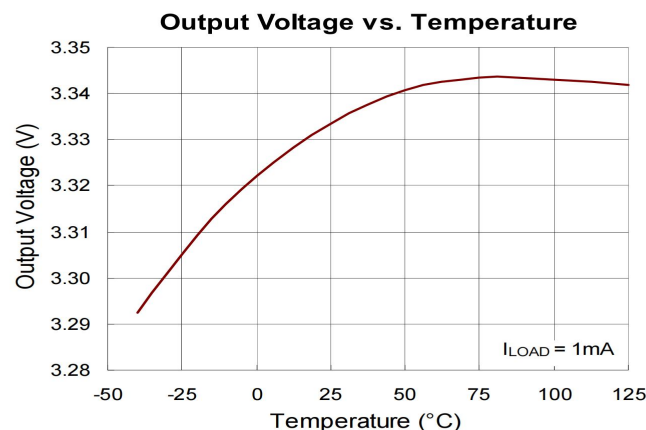


Figure 4. Temperature Coefficient of Adjustable Output Voltage

The minimum recommended 50μA in the resistor divider makes the application no longer an ultra low quiescent LDO. Figure 5 is another fine adjustable output voltage application can keep the LDO still operating in low power consumption. The fine tune range is recommended to be less than 50mV ( $R1 \leq 91k\Omega$ ) in order to keep a good temperature coefficient of the output voltage.

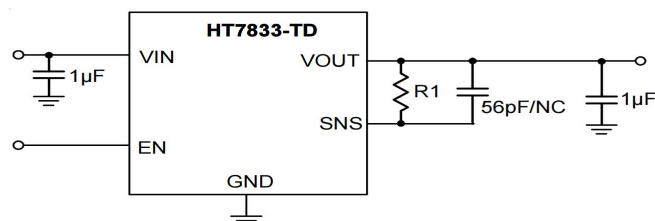


Figure 5. Fine Adjustable Output Voltage Application Circuit

There isn't extra current consumption in the above application. But the temperature coefficient of output voltage will be degraded by the input current at SNS pin. If the tuning range is larger than 50mV, a compensation capacitor (56pF) is required to keep the stability of output voltage. The fine adjustable output voltage is calculated using the formula given in equation 2 :

$$V_{OUT} = V_{SNS} + I_{SNS} \times R1 \quad (2)$$

where  $I_{SNS}$  is the input Current at SNS pin (typical 550nA at room temperature) and  $V_{SNS}$  is determined by the output voltage selections in the ordering information of the HT7833-TD.

## Current Limit

The RT9080 contains an independent current limiter, which monitors and controls the pass transistor's gate voltage, limiting the output current to 1.1A (typ.). The current limiting level is reduced to around 0.6A named fold-back current limit when the output voltage is further decreased. The output can be shorted to ground indefinitely without damaging the part.

## Thermal Considerations

For continuous operation, do not exceed absolute maximum junction temperature. The maximum power dissipation depends on the thermal resistance of the IC package, PCB layout, rate of surrounding airflow, and difference between junction and ambient temperature. The maximum power dissipation can be calculated by the following formula :

$$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$$

where  $T_{J(MAX)}$  is the maximum junction temperature,  $T_A$  is the ambient temperature, and  $\theta_{JA}$  is the junction to ambient thermal resistance.

For recommended operating condition specifications the maximum junction temperature is 125°C and  $T_A$  is the ambient temperature. The junction to ambient thermal resistance,  $\theta_{JA}$ , is layout dependent. For TSOT-23-5 package, the thermal resistance,  $\theta_{JA}$ , is 230.6°C/W on a standard JEDEC 51-7 four-layer thermal test board. For ZQFN-4L 1x1 (ZDFN-4L 1x1) package, the thermal resistance,  $\theta_{JA}$ , is 226°C/W on a two-layer Richtek evaluation board. The maximum power dissipation at  $T_A = 25^\circ\text{C}$  can be calculated by the following formula :

$$P_{D(MAX)} = (125^\circ\text{C} - 25^\circ\text{C}) / (230.6^\circ\text{C/W}) = 0.43\text{W for TSOT-23-5 package}$$

$$P_{D(MAX)} = (125^\circ\text{C} - 25^\circ\text{C}) / (226^\circ\text{C/W}) = 0.44\text{W for ZQFN-4L 1x1 (ZDFN-4L 1x1) package}$$

The maximum power dissipation depends on the operating ambient temperature for fixed  $T_{J(MAX)}$  and thermal resistance,  $\theta_{JA}$ . The derating curve in Figure 6 allows the designer to see the effect of rising ambient temperature on the maximum power dissipation.

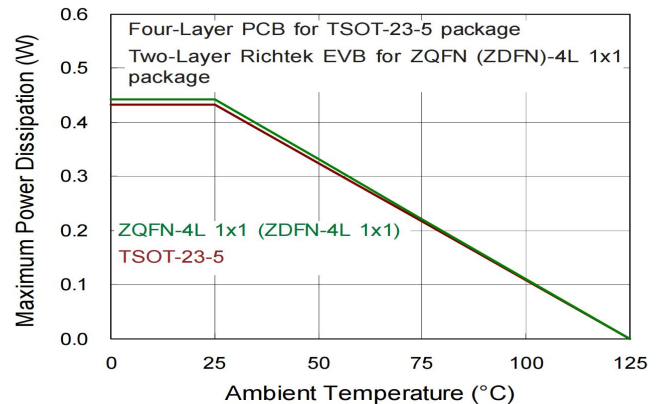
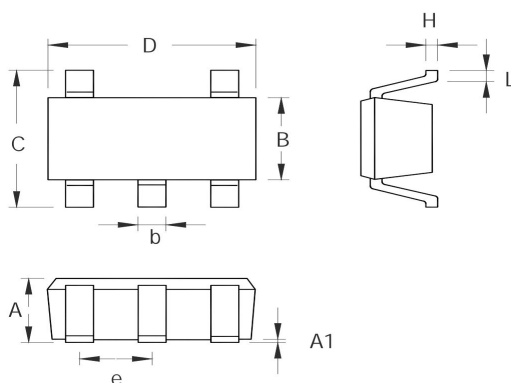


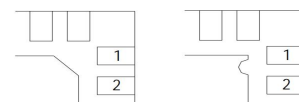
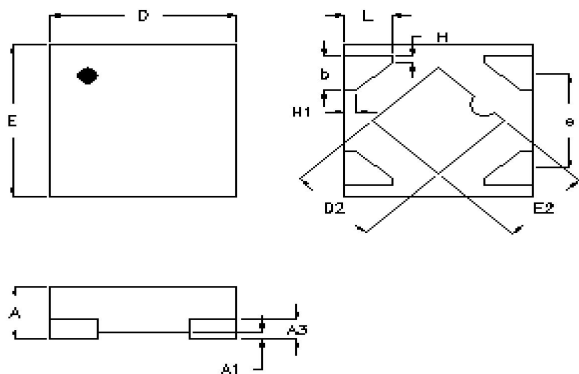
Figure 6. Derating Curve of Maximum Power Dissipation

## Outline Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	1.000	0.028	0.039
A1	0.000	0.100	0.000	0.004
B	1.397	1.803	0.055	0.071
b	0.300	0.559	0.012	0.022
C	2.591	3.000	0.102	0.118
D	2.692	3.099	0.106	0.122
e	0.838	1.041	0.033	0.041
H	0.080	0.254	0.003	0.010
L	0.300	0.610	0.012	0.024

**TSOT-23-5 Surface Mount Package**



### DETAILA

Pin #1 ID and Tie Bar Mark Options

Note : The configuration of the Pin #1 identifier is optional, but must be located within the zone indicated.

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.300	0.400	0.012	0.016
A1	0.000	0.050	0.000	0.002
A3	0.117	0.162	0.005	0.006
b	0.175	0.275	0.007	0.011
D	0.900	1.100	0.035	0.043
D2	0.450	0.550	0.018	0.022
E	0.900	1.100	0.035	0.043
E2	0.450	0.550	0.018	0.022
e	0.625		0.025	
L	0.200	0.300	0.008	0.012
H	0.039		0.002	
H1	0.064		0.003	

Z-Type 4L QFN 1x1 Package